Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L39	5	(substrate work adj piece workpiece target semiconductor wafer) near10 (block$3 deflect$3 shield$3 shutter$3 protect$3) near5 (plasma discharge) and (plasma discharge) near10 (diffus$4 spread$4)	USOCR	OR	ON	2005/08/21 11:57
L34	562	29 and (substrate work adj piece workpiece target semiconductor wafer) with (block$3 deflect$3 shield$3 shutter$3 protect$3) with (plasma discharge) and (plasma discharge) with (diffus$4 spread$4)	US-PGPUB; USPAT	OR	ON	2005/08/21 11:56
L38	40	("0898346" | "2378476" | "3294669" | "3369989" | "3604970" | "3625848" | "3678889" | "3691053" | "3709809" | "3736175" | "3783231" | "3793179" | "4094764" | "4197175" | "4222838" | "4333962" | "4361114" | "4410407" | "4448799" | "4466872" | "4511593" | "4511594" | "4556471" | "4622452" | "4681773" | "4724058" | "4801839" | "4828872" | "4856457" | "4959242" | "5100526").PN. OR ("5656091"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/21 11:48
L37	19	("4511593").URPN.	USPAT	OR	ON	2005/08/21 11:45
L36	9	("2378476" | "3625848" | "3677924" | "3900585" | "4094764" | "4279216" | "4351855").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/21 11:45
L35	413	34 not 30 not 19 not 17 not 15	US-PGPUB; USPAT	OR	ON	2005/08/21 11:40
L33	3225	29 and (substrate work adj piece workpiece target semiconductor wafer) with (block$3 deflect$3 shield$3 shutter$3 protect$3) with (plasma discharge)	US-PGPUB; USPAT	OR	ON	2005/08/21 11:40
L31	439	30 not 19 not 17 not 15	US-PGPUB; USPAT	OR	ON	2005/08/21 11:40
L30	549	29 and (substrate work adj piece workpiece target semiconductor wafer) with (block$3 deflect$3 shield$3 shutter$3 protect$3) with (ground$3 earth)	US-PGPUB; USPAT	OR	ON	2005/08/21 11:39

L32	5	("3640812" | "3784458" | "5178739" | "5382339" | "6051113").PN. OR ("6444103"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/21 11:35
L18	838	17 not 15	US-PGPUB; USPAT	OR	ON	2005/08/21 11:28
S78	35427	S74 and plasma.ti,ab,clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/21 11:26
L29	76660	L28 and plasma	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/21 11:26
L28	633838	(("118") or ("156") or ("216") or ("438") or ("427") or ("315")). CLAS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/21 11:26
L11	180	(substrate work adj piece workpiece target semiconductor wafer) near10 ((far opposite) near2 (side face)) near10 (electrode anode cathode) and (plasma discharge)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/21 11:25
L27	34	("3718572" | "3956093" | "4060470" | "4094761").PN. OR ("4324631").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/21 11:03
L26	28	("4361472" | "4401546" | "4422896" | "4434038" | "4448653" | "4461688" | "4601806" | "4606802").PN. OR ("4673482").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/21 10:56
L25	22	("3835007" | "3941692" | "3945903" | "4342632" | "4597828" | "4647361" | "4702941").PN. OR ("4964962"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/21 10:53
L24	5	("5417798" | "6006694" | "6026764" | "6170431" | "6173674").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/21 10:43
L23	1	("6521081")	USPAT	OR	ON	2005/08/21 10:43
L20	667	19 not 18	US-PGPUB; USPAT	OR	ON	2005/08/21 10:30

L19	729	(substrate work adj piece workpiece target semiconductor wafer) with (shutter shield) with (electrode anode cathode) same (plasma discharge)	US-PGPUB; USPAT	OR	ON	2005/08/21 10:30
L17	883	(substrate work adj piece workpiece target semiconductor wafer) with (outside behind) with (electrode anode cathode) same (plasma discharge)	US-PGPUB; USPAT	OR	ON	2005/08/21 10:29
L1	510	(substrate work adj piece workpiece target semiconductor wafer) near3 (outside) near3 (electrode anode cathode)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/21 09:58
L16	44	("3762941" | "4012307" | "4430547" | "4705593" | "4708766" | "4749440" | "4857382" | "4921157" | "5000819" | "5045166" | "5120568" | "5126164" | "5147520" | "5178682" | "5201995" | "5225659" | "5240559" | "5290378" | "5292370" | "5316739" | "5340618" | "5368685" | "5384167" | "5391855" | "5399830" | "5407121" | "5449432" | "5499754" | "5597438").PN. OR ("5753886"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/21 09:53
L15	398	(substrate work adj piece workpiece target semiconductor wafer) with ((far opposite) near2 (side face)) with (electrode anode cathode) same (plasma discharge)	US-PGPUB; USPAT	OR	ON	2005/08/21 09:48
L13	2230	(substrate work adj piece workpiece target semiconductor wafer) near10 ((far opposite) near2 (side face)) near10 (electrode anode cathode) and (plasma discharge)	US-PGPUB; USPAT	OR	ON	2005/08/21 09:48
L12	178	11 not 8 not 1 not 2 not 4	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/21 09:41
L9	271	8 not 1 not 2 not 4	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/21 09:41
L8	367	(substrate work adj piece workpiece target semiconductor wafer) near10 (outside) near10 (electrode anode cathode) and (plasma discharge)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/21 09:40

L10	1	1987-317249.NRAN.	DERWENT	OR	ON	2005/08/21 09:35
L7	1845	(substrate work adj piece workpiece target semiconductor wafer) and (outside) and (electrode anode cathode) and (plasma discharge)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/21 09:31
S15 2	13606	(substrate work adj piece workpiece target semiconductor wafer) and (outside) and (electrode anode cathode)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/21 09:30
S15 5	314	(substrate work adj piece workpiece target semiconductor wafer) near2 (outside) near3 (electrode anode cathode)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/21 09:22
L6	332	3 5	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/21 09:22
L5·	136	L4 not L1 not L2	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/21 09:22
L4	459	(substrate work adj piece workpiece target semiconductor wafer) near2 (outside) near5 (electrode anode cathode)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/21 09:22
L3	196	L1 not L2	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/21 09:22
L2	314	(substrate work adj piece workpiece target semiconductor wafer) near2 (outside) near3 (electrode anode cathode)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/21 09:22
S15 6	459	(substrate work adj piece workpiece target semiconductor wafer) near2 (outside) near5 (electrode anode cathode)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 19:53
S15 4	510	(substrate work adj piece workpiece target semiconductor wafer) near3 (outside) near3 (electrode anode cathode)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 19:53
S15 3	708	(substrate work adj piece workpiece target semiconductor wafer) near3 (outside) near5 (electrode anode cathode)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 19:53
S15 1	121016	(substrate work adj piece workpiece target semiconductor wafer) and (outside) and (electrode anode cathode)	US-PGPUB; USPAT	OR	ON	2005/08/19 19:53

S14 7	8470	(substrate work adj piece workpiece target semiconductor wafer) with (outside) with (electrode anode cathode)	US-PGPUB; USPAT	OR	ON	2005/08/19 19:53
S15 0	0	("2005/0061444").URPN.	USPAT	OR	ON	2005/08/19 19:50
S14 9	43	("4597844").URPN.	USPAT	OR	ON	2005/08/19 19:32
S14 8	765	S147 and plasma.ti,ab,clm.	US-PGPUB; USPAT	OR	ON	2005/08/19 19:30
S14 5	13383	(substrate work adj piece workpiece target semiconductor wafer) with (outside) with (electrode anode cathode)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 19:29
S14 4	48119	(substrate work adj piece workpiece target semiconductor wafer) with (outside opposite) with (electrode anode cathode)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 19:29
S18	104	(156/345.54).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/19 19:27
S14 3	4	("5698328" | "5993919").PN. OR ("6200652").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/19 17:38
S14 2	27	("4070264" | "4223048" | "4289598" | "4492716" | "4633809" | "4633811" | "4643952" | "4676195" | "4735633" | "4950376").PN. OR ("5039376").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/19 17:35
S14 1	3	(("5039376") or ("6200652") or ("6852195")).PN.	US-PGPUB; USPAT	OR	OFF	2005/08/19 17:34
S13 9	3	(("4581118") or ("5891311") or ("6200431")).PN.	US-PGPUB; USPAT	OR	OFF	2005/08/19 17:34
S14 0	2	JP-62027562-$.did.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 17:16
S13 6	1	("4581118").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/08/18 20:38